HM514800D Series
HM51S4800D Series

524,288-word × 8-bit Dynamic RAM

HITACHI

ADE-203-687(Z)
Preliminary
Rev. 0.0
Dec. 3, 1996

Description

The Hitachi HM51(S)4800D are CMOS dynamic RAM organized as 524,288-word × 8-bit. HM51(S)4800D have realized higher density, higher performance and various functions by employing 0.8 µm CMOS process technology and some new CMOS circuit design technologies. The HM51(S)4800D offer Fast Page Mode as a high speed access mode. They have the package variations of standard 400-mil 28-pin plastic SOJ and standard 400-mil 28-pin plastic TSOPII. Internal refresh timer enables HM51S4800D self refresh operation.

Features

- Single 5 V (± 10%)
- Access time: 60 ns/70 ns/80 ns (max)
- Power dissipation
  - Active mode: 605 mW/550 mW/495 mW (max)
  - Standby mode: 11 mW (max)
    : 1.1 mW (max) (L-version)
- Fast page mode capability
- Refresh cycles
  - 1,024 refresh cycles: 16 ms
    : 128 ms (L-version)
- 2 variations of refresh
  - $\overline{\text{RAS}}$-only refresh
  - $\overline{\text{CAS}}$-before-$\overline{\text{RAS}}$ refresh
- Battery backup operation (L-version)
- Self refresh operation (HM51S4800D)

Preliminary: This document contains information on a new product. Specifications and information contained herein are subject to change without notice.

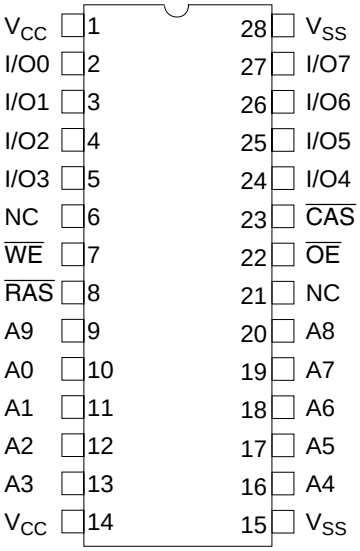
Hitachi semiconductor

Ordering Information

Type No.	Access time	Package
HM514800DJ-6	60 ns	400-mil 28-pin plastic SOJ (CP-28D)
HM514800DJ-7	70 ns	
HM514800DJ-8	80 ns	
HM514800DLJ-6	60 ns	
HM514800DLJ-7	70 ns	
HM514800DLJ-8	80 ns	
HM51S4800DJ-6	60 ns	
HM51S4800DJ-7	70 ns	
HM51S4800DJ-8	80 ns	
HM51S4800DLJ-6	60 ns	
HM51S4800DLJ-7	70 ns	
HM51S4800DLJ-8	80 ns	
HM514800DTT-6	60 ns	400-mil 28-pin plastic TSOP II (TTP-28D)
HM514800DTT-7	70 ns	
HM514800DTT-8	80 ns	
HM514800DLTT-6	60 ns	
HM514800DLTT-7	70 ns	
HM514800DLTT-8	80 ns	
HM51S4800DTT-6	60 ns	
HM51S4800DTT-7	70 ns	
HM51S4800DTT-8	80 ns	
HM51S4800DLTT-6	60 ns	
HM51S4800DLTT-7	70 ns	
HM51S4800DLTT-8	80 ns	

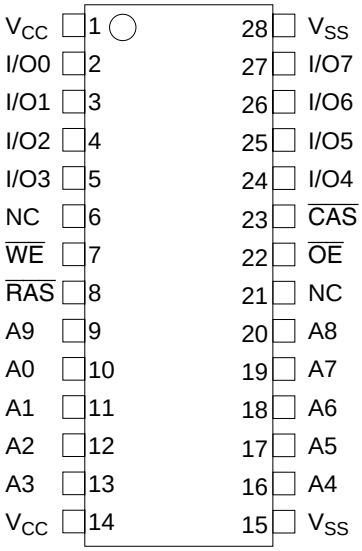
Pin Arrangement

HM514800DJ / DLJ Series
HM51S4800DJ / DLJ Series



(Top view)

HM514800DTT / DLTT Series
HM51S4800DTT / DLTT Series

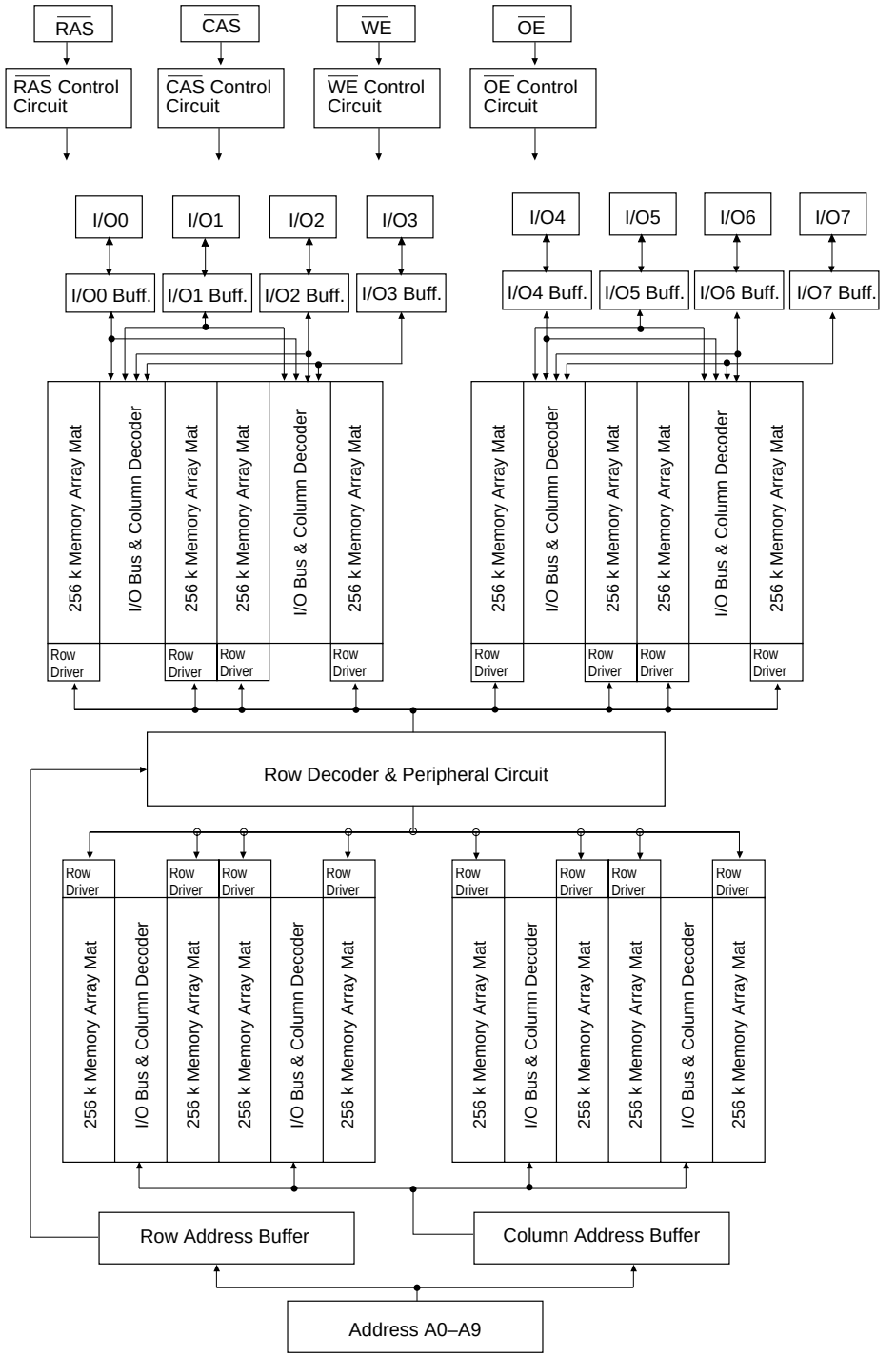


(Top view)

Pin Description

Pin name	Function	
A0 to A9	Address input	
	– Row address	A0 to A9
	– Column address	A0 to A8
	– Refresh address	A0 to A9
I/O0 to I/O7	Data-input/output	
$\overline{RAS}$	Row address strobe	
$\overline{CAS}$	Column address strobe	
$\overline{WE}$	Read/write enable	
$\overline{OE}$	Output enable	
V_{cc}	Power supply	
V_{ss}	Ground	
NC	No connection	

Block Diagram



Operation Mode

The HM51(S)4800D series has the following 11 operation modes.

1. Read cycle
2. Early write cycle
3. Delayed write cycle
4. Read-modify-write cycle
5. $\overline{\text{RAS}}$-only refresh cycle
6. $\overline{\text{CAS}}$-before-$\overline{\text{RAS}}$ refresh cycle
7. Self refresh cycle (HM51S4800D)
8. Fast page mode read cycle
9. Fast page mode early write cycle
10. Fast page mode delayed write cycle
11. Fast page mode read-modify-write cycle

Inputs

$\overline{\text{RAS}}$	$\overline{\text{CAS}}$	$\overline{\text{WE}}$	$\overline{\text{OE}}$	Output	Operation
H	H	D	D	Open	Standby
H	L	H	L	Valid	Standby
L	L	H	L	Valid	Read cycle
L	L	L[*2]	D	Open	Early write cycle
L	L	L[*2]	H	Undefined	Delayed write cycle
L	L	H to L	L to H	Valid	Read-modify-write cycle
L	H	D	D	Open	$\overline{\text{RAS}}$-only refresh cycle
H to L	L	D	D	Open	$\overline{\text{CAS}}$-before-$\overline{\text{RAS}}$ refresh cycle Self refresh cycle (HM51S4800D)
L	H to L	H	L	Valid	Fast page mode read cycle
L	H to L	L[*2]	D	Open	Fast page mode early write cycle
L	H to L	L[*2]	H	Undefined	Fast page mode delayed write cycle
L	H to L	H to L	L to H	Valid	Fast page mode read-modify-write cycle
L	L	H	H	Open	Read cycle (Output disabled)

Notes: 1. H: High (inactive) L: Low (active) D: H or L
2. $t_{WCS} \geq 0$ ns Early write cycle
$t_{WCS} < 0$ ns Delayed write cycle

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Voltage on any pin relative to V_{SS}	V_T	–1.0 to +7.0	V
Supply voltage relative to V_{SS}	V_{CC}	–1.0 to +7.0	V
Short circuit output current	Iout	50	mA
Power dissipation	P_T	1.0	W
Operating temperature range	Topr	0 to +70	°C
Storage temperature range	Tstg	–55 to +125	°C

Recommended DC Operating Conditions (Ta = 0 to +70°C)

Parameter	Symbol	Min	Typ	Max	Unit	Notes
Supply voltage	V_{SS}	0	0	0	V	2
	V_{CC}	4.5	5.0	5.5	V	1, 2
Input high voltage	V_{IH}	2.4	—	6.5	V	1
Input low voltage	V_{IL}	–1.0	—	0.8	V	1

Notes: 1. All voltage referred to V_{SS}.
2. The supply voltage with all V_{CC} pins must be on the same level.
The supply voltage with all V_{SS} pins must be on the same level.

DC Characteristics (Ta = 0 to +70°C, V_{CC} = 5 V ± 10%, V_{SS} = 0 V) *5

		HM514800D, HM51S4800D							
		-6		-7		-8			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Test conditions
Operating current*1, 2	I_{CC1}	—	120	—	110	—	100	mA	$\overline{RAS}$, $\overline{CAS}$ cycling t_{RC} = min
Standby current	I_{CC2}	—	2	—	2	—	2	mA	TTL interface $\overline{RAS}$, $\overline{CAS}$ = V_{IH} Dout = High-Z
		—	1	—	1	—	1	mA	CMOS interface $\overline{RAS}$, $\overline{CAS}$ ≥ V_{CC} –0.2 V Dout = High-Z
Standby current (L-version)	I_{CC2}	—	200	—	200	—	200	µA	CMOS interface $\overline{RAS}$, $\overline{CAS}$ ≥ V_{CC} –0.2 V Dout = High-Z
$\overline{RAS}$-only refresh current*2	I_{CC3}	—	120	—	110	—	100	mA	t_{RC} = min

DC Characteristics (Ta = 0 to +70°C, V_{CC} = 5 V ± 10%, V_{SS} = 0 V) [*5] (cont)

		HM514800D, HM51S4800D							
		-6		-7		-8			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Test Conditions
$\overline{CAS}$-before-$\overline{RAS}$ refresh current[*4]	I_{CC6}	—	120	—	110	—	100	mA	t_{RC} = min
Fast page mode current[*1, 3]	I_{CC7}	—	120	—	110	—	100	mA	t_{PC} = min
Battery backup current[*4] (Standby with CBR refresh) (L-version)	I_{CC10}	—	300	—	300	—	300	µA	Standby: CMOS interface Dout = High-Z CBR refresh: t_{RC} = 125 µs $t_{RAS} \leq$ 1 µs, $\overline{CAS}$ = V_{IL} $\overline{WE}$ = V_{IH}
Self refresh mode current (HM51S4800D)	I_{CC11}	—	1	—	1	—	1	mA	CMOS interface $\overline{RAS}$, $\overline{CAS} \leq$ 0.2 V Dout = High-Z
Self refresh mode current (HM51S4800DL)	I_{CC11}	—	200	—	200	—	200	µA	CMOS interface $\overline{RAS}$, $\overline{CAS} \leq$ 0.2 V Dout = High-Z
Input leakage current	I_{LI}	–10	10	–10	10	–10	10	µA	0 V ≤ Vin ≤ 6.5 V
Output leakage current	I_{LO}	–10	10	–10	10	–10	10	µA	0 V ≤ Vout ≤ 6.5 V Dout = disable
Output high voltage	V_{OH}	2.4	V_{CC}	2.4	V_{CC}	2.4	V_{CC}	V	High Iout = –5 mA
Output low voltage	V_{OL}	0	0.4	0	0.4	0	0.4	V	Low Iout = 4.2 mA

Notes: 1. I_{CC} depends on output load condition when the device is selected I_{CC} max is specified at the output open condition.
2. Address can be changed once or less while $\overline{RAS}$ = V_{IL}.
3. Address can be changed once or less while $\overline{CAS}$ = V_{IH}.
4. $V_{IH} \geq V_{CC}$ –0.2 V, $V_{IL} \leq$ 0.2 V; Address can be changed once or less while $\overline{CAS}$ = V_{IL}.
5. The supply voltage with all V_{CC} pins must be on the same level.
The supply voltage with all V_{SS} pins must be on the same level.

Capacitance (Ta = 25°C, V_{CC} = 5 V ± 10%)

Parameter	Symbol	Typ	Max	Unit	Notes
Input capacitance (Address)	C_{I1}	—	5	pF	1
Input capacitance (Clocks)	C_{I2}	—	7	pF	1
Output capacitance (Data-in, Data-out)	$C_{I/O}$	—	10	pF	1, 2

Notes: 1. Capacitance measured with Boonton Meter or effective capacitance measuring method.
2. $\overline{CAS}$ = V_{IH} to disable Dout.

AC Characteristics (Ta = 0 to 70°C, V_{CC} = 5 V ± 10%, V_{SS} = 0 V) [*1, *14, *15]

Test conditions

- Input rise and fall time: 5 ns
- Input levels: 0 V, 3 V
- Input timing reference levels: 0.8 V, 2.4 V
- Output load: 2 TTL gate + C_L (100 pF) (Including scope and jig)

Read, Write, Read-Modify-Write and Refresh Cycles (Common Parameters)

		HM514800D, HM51S4800D							
		-6		-7		-8			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
Random read or write cycle time	t_{RC}	110	—	130	—	150	—	ns	
$\overline{RAS}$ precharge time	t_{RP}	40	—	50	—	60	—	ns	
$\overline{RAS}$ pulse width	t_{RAS}	60	10000	70	10000	80	10000	ns	
$\overline{CAS}$ pulse width	t_{CAS}	15	10000	20	10000	20	10000	ns	
Row address setup time	t_{ASR}	0	—	0	—	0	—	ns	
Row address hold time	t_{RAH}	10	—	10	—	10	—	ns	
Column address setup time	t_{ASC}	0	—	0	—	0	—	ns	
Column address hold time	t_{CAH}	15	—	15	—	15	—	ns	
$\overline{RAS}$ to $\overline{CAS}$ delay time	t_{RCD}	20	45	20	50	20	60	ns	8
$\overline{RAS}$ to column address delay time	t_{RAD}	15	30	15	35	15	40	ns	9
$\overline{RAS}$ hold time	t_{RSH}	20	—	20	—	20	—	ns	
$\overline{CAS}$ hold time	t_{CSH}	60	—	70	—	80	—	ns	
$\overline{CAS}$ to $\overline{RAS}$ precharge time	t_{CRP}	10	—	10	—	10	—	ns	
$\overline{OE}$ to Din delay time	t_{ODD}	15	—	20	—	20	—	ns	
$\overline{OE}$ delay time from Din	t_{DZO}	0	—	0	—	0	—	ns	
$\overline{CAS}$ setup time from Din	t_{DZC}	0	—	0	—	0	—	ns	
Transition time (rise and fall)	t_T	3	50	3	50	3	50	ns	7
Refresh period	t_{REF}	—	16	—	16	—	16	ms	
Refresh period (L-version)	t_{REF}	—	128	—	128	—	128	ms	

Read Cycle

		HM514800D, HM51S4800D							
		-6		-7		-8			
Parameter	**Symbol**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Unit**	**Notes**
Access time from $\overline{RAS}$	t_{RAC}	—	60	—	70	—	80	ns	2, 3
Access time from $\overline{CAS}$	t_{CAC}	—	15	—	20	—	20	ns	3, 4, 13
Access time from address	t_{AA}	—	30	—	35	—	40	ns	3, 5, 13
Access time from $\overline{OE}$	t_{OAC}	—	15	—	20	—	20	ns	
Read command setup time	t_{RCS}	0	—	0	—	0	—	ns	
Read command hold time to $\overline{CAS}$	t_{RCH}	0	—	0	—	0	—	ns	
Read command hold time to $\overline{RAS}$	t_{RRH}	0	—	0	—	0	—	ns	
Column address to $\overline{RAS}$ lead time	t_{RAL}	30	—	35	—	40	—	ns	
Output buffer turn-off time	t_{OFF1}	0	15	0	15	0	15	ns	6
Output buffer turn-off to $\overline{OE}$	t_{OFF2}	0	15	0	15	0	15	ns	6
$\overline{CAS}$ to Din delay time	t_{CDD}	15	—	15	—	15	—	ns	

Write Cycle

		HM514800D, HM51S4800D							
		-6		-7		-8			
Parameter	**Symbol**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Unit**	**Notes**
Write command setup time	t_{WCS}	0	—	0	—	0	—	ns	10
Write command hold time	t_{WCH}	15	—	15	—	15	—	ns	
Write command pulse width	t_{WP}	10	—	10	—	10	—	ns	
Write command to $\overline{RAS}$ lead time	t_{RWL}	15	—	20	—	20	—	ns	
Write command to $\overline{CAS}$ lead time	t_{CWL}	15	—	20	—	20	—	ns	
Data-in setup time	t_{DS}	0	—	0	—	0	—	ns	11
Data-in hold time	t_{DH}	15	—	15	—	15	—	ns	11
$\overline{CAS}$ to $\overline{OE}$ delay time	t_{COD}	—	0	—	0	—	0	ns	18

Read-Modify-Write Cycle

		HM514800D, HM51S4800D							
		-6		-7		-8			
Parameter	**Symbol**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Unit**	**Notes**
Read-modify-write cycle time	t_{RWC}	150	—	180	—	200	—	ns	
$\overline{RAS}$ to $\overline{WE}$ delay time	t_{RWD}	80	—	95	—	105	—	ns	10
$\overline{CAS}$ to $\overline{WE}$ delay time	t_{CWD}	35	—	45	—	45	—	ns	10
Column address to $\overline{WE}$ delay time	t_{AWD}	50	—	60	—	65	—	ns	10
$\overline{OE}$ hold time from $\overline{WE}$	t_{OEH}	15	—	20	—	20	—	ns	

Refresh Cycle

		HM514800D, HM51S4800D							
		-6		-7		-8			
Parameter	**Symbol**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Unit**	**Notes**
$\overline{CAS}$ setup time (CBR refresh cycle)	t_{CSR}	10	—	10	—	10	—	ns	
$\overline{CAS}$ hold time (CBR refresh cycle)	t_{CHR}	10	—	10	—	10	—	ns	
$\overline{RAS}$ precharge to $\overline{CAS}$ hold time	t_{RPC}	10	—	10	—	10	—	ns	
$\overline{CAS}$ precharge time in normal mode	t_{CPN}	10	—	10	—	10	—	ns	

Fast Page Mode Cycle

		HM514800D, HM51S4800D							
		-6		-7		-8			
Parameter	**Symbol**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Unit**	**Notes**
Fast page mode cycle time	t_{PC}	40	—	45	—	50	—	ns	
Fast page mode $\overline{CAS}$ precharge time	t_{CP}	10	—	10	—	10	—	ns	
Fast page mode $\overline{RAS}$ pulse width	t_{RASC}	—	100000	—	100000	—	100000	ns	12
Access time from $\overline{CAS}$ precharge	t_{ACP}	—	35	—	40	—	45	ns	3, 13
$\overline{RAS}$ hold time from $\overline{CAS}$ precharge	t_{RHCP}	35	—	40	—	45	—	ns	

Fast Page Mode Read-Modify-Write Cycle

		HM514800D, HM51S4800D							
		-6		-7		-8			
Parameter	**Symbol**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Unit**	**Notes**
Fast page mode read-modify-write cycle $\overline{CAS}$ precharge to $\overline{WE}$ delay time	t_{CPW}	55	—	65	—	70	—	ns	
Fast page mode read-modify-write cycle time	t_{PCM}	80	—	95	—	100	—	ns	

Self-Refresh Mode

		HM514800D, HM51S4800D							
		-6		-7		-8			
Parameter	**Symbol**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Unit**	**Notes**
$\overline{RAS}$ pulse width (self-refresh)	t_{RASS}	100	—	100	—	100	—	µs	19, 20, 21, 22
$\overline{RAS}$ precharge time (self-refresh)	t_{RPS}	110	—	130	—	150	—	ns	
$\overline{CAS}$ hold time (self-refresh)	t_{CHS}	-50	—	-50	—	-50	—	ns	

Notes:
1. AC measurements assume t_T = 5 ns.
2. Assumes that $t_{RCD} \leq t_{RCD}$ (max) and $t_{RAD} \leq t_{RAD}$ (max). If t_{RCD} or t_{RAD} is greater than the maximum recommended value shown in this table, t_{RAC} exceeds the value shown.
3. Measured with a load circuit equivalent to 2 TTL loads and 100 pF.
4. Assumes that $t_{RCD} \geq t_{RCD}$ (max) and $t_{RAD} \leq t_{RAD}$ (max).
5. Assumes that $t_{RCD} \leq t_{RCD}$ (max) and $t_{RAD} \geq t_{RAD}$ (max).
6. t_{OFF} (max) defines the time at which the output achieves the open circuit condition and is not referred to output voltage levels.
7. V_{IH} (min) and V_{IL} (max) are reference levels for measuring timing of input signals. Also, transition times are measured between V_{IH} and V_{IL}.
8. Operation with the t_{RCD} (max) limit insures that t_{RAC} (max) can be met, t_{RCD} (max) is specified as a reference point only, if t_{RCD} is greater than the specified t_{RCD} (max) limit, then access time is controlled exclusively by t_{CAC}.
9. Operation with the t_{RAD} (max) limit insures that t_{RAC} (max) can be met, t_{RAD} (max) is specified as a reference point only, if t_{RAD} is greater than the specified t_{RAD} (max) limit, then access time is controlled exclusively by t_{AA}.
10. t_{WCS}, t_{RWD}, t_{CWD} and t_{AWD} are not restrictive operating parameters. They are included in the data sheet as electrical characteristics only: if $t_{WCS} \geq t_{WCS}$ (min), the cycle is an early write cycle and the data out pin will remain open circuit (high impedance) throughout the entire cycle; if $t_{RWD} \geq t_{RWD}$ (min), $t_{CWD} \geq t_{CWD}$ (min), $t_{AWD} \geq t_{AWD}$ (min) and $t_{CPW} \geq t_{CPW}$ (min), the cycle is a read-modify-write and the data output will contain data read from the selected cell; if neither of the above sets of conditions is satisfied, the condition of the data out (at access time) is indeterminate.
11. These parameters are referred to $\overline{CAS}$ leading edge in an early write cycle and to $\overline{WE}$ leading edge in a delayed write or a read-modify-write cycle.
12. t_{RASC} defines $\overline{RAS}$ pulse width in fast page mode cycles.
13. Access time is determined by the longest among t_{AA}, t_{CAC} and t_{ACP}.
14. An initial pause of 100 µs is required after power up followed by a minimum of eight initialization cycles ($\overline{RAS}$-only refresh cycle or $\overline{CAS}$-before-$\overline{RAS}$ refresh cycle). If the internal refresh counter is used, a minimum of eight $\overline{CAS}$-before-$\overline{RAS}$ refresh cycles is required.
15. In delayed write or read-modify-write cycles, $\overline{OE}$ must disable output buffer prior to applying data to the device.
16. Either t_{RCH} or t_{RRH} must be satisfied for a read cycle.
17. The supply voltage with all V_{CC} pins must be on the same level.
    The supply voltage with all V_{SS} pins must be on the same level.
18. Do not enable Dout buffer when using delayed write timing.
19. Please do not use t_{RASS} timing, 10 µs $\leq t_{RASS} \leq$100 µs. During this period, the device is in transition state from normal operation mode to self refresh mode. if $t_{RASS} \geq$ 100 µs, then $\overline{RAS}$ precharge time should use t_{RPS} instead of t_{RP}.
20. If you use distributed CBR refresh mode with 15.6 µs interval in normal read/write cycle, CBRrefresh should be executed within 15.6 µs immediately after exiting from and before entering into self refresh mode.
21. If you use $\overline{RAS}$ only refresh or CBR burst refresh mode in normal read/write cycle, 1024 cycles of distributed CBR refresh with 15.6 µs interval should be executed within 16 ms immediately after exiting from and before entering into the self refresh mode.
22. Repetitive self refresh mode without refreshing all memory is not allowed. Once you exit from self refresh mode, all memory cells need to be refreshed before re-entering the self refresh mode again.

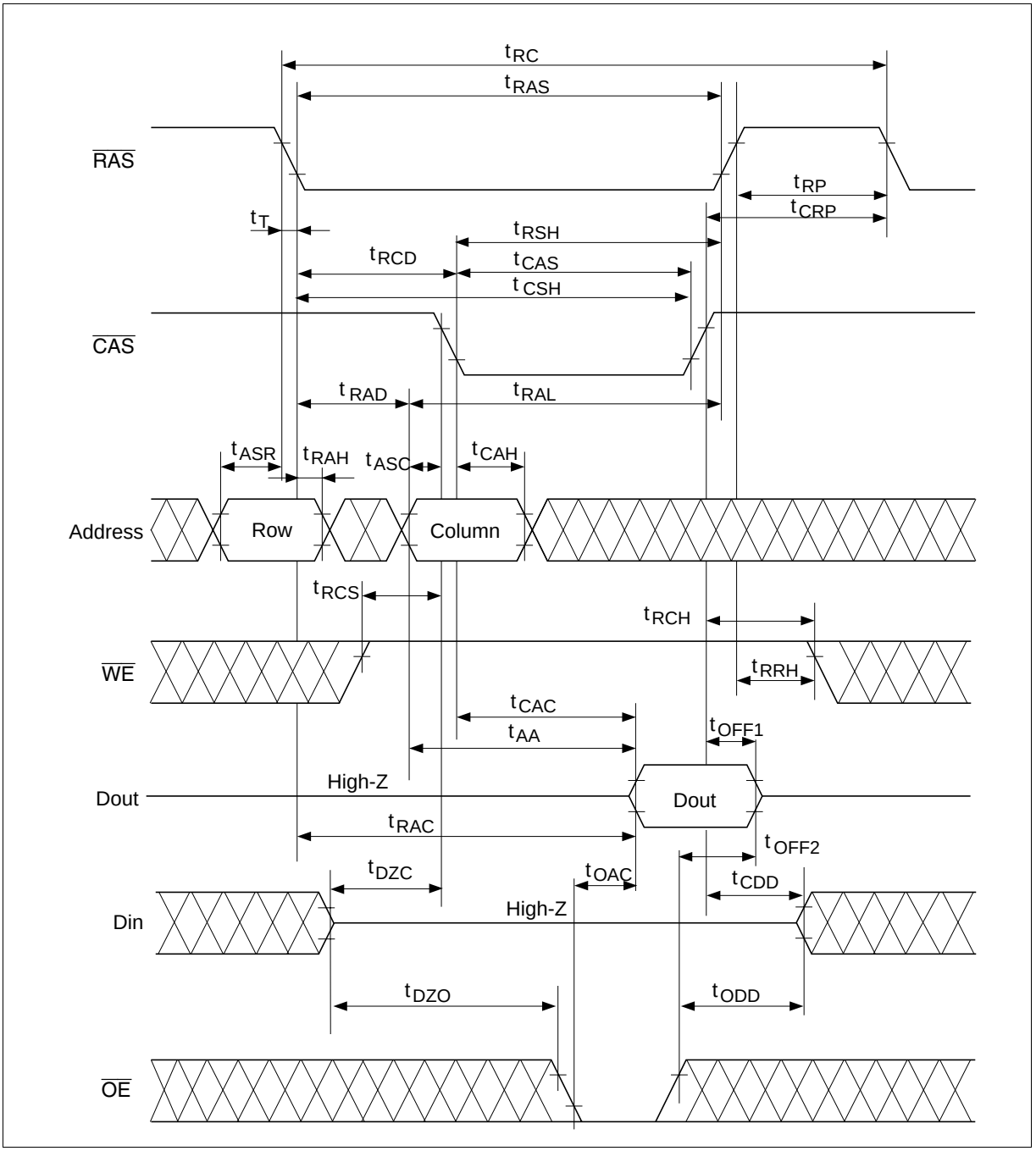
23. XXX H or L (H: V_{IH} (min) ≤ V_{IN} ≤ V_{IH} (max), L: V_{IL} (min) ≤ V_{IN} ≤ V_{IL} (max))

    /////// Invalid Dout

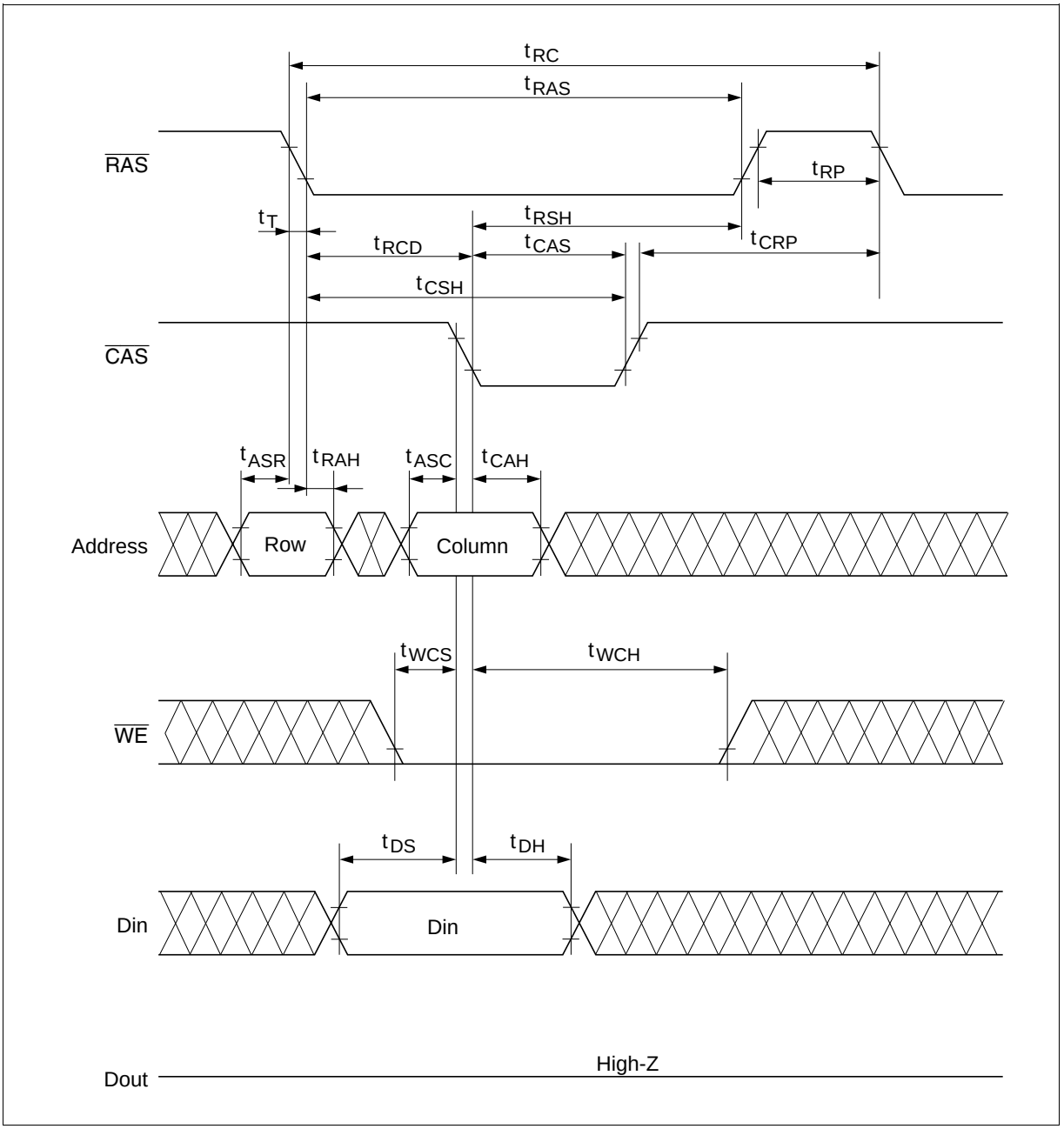
    When the address, clock and input pins are not described on timing waveforms, their pins must be applied V_{IH} or V_{IL}.

Timing Waveforms*[23]

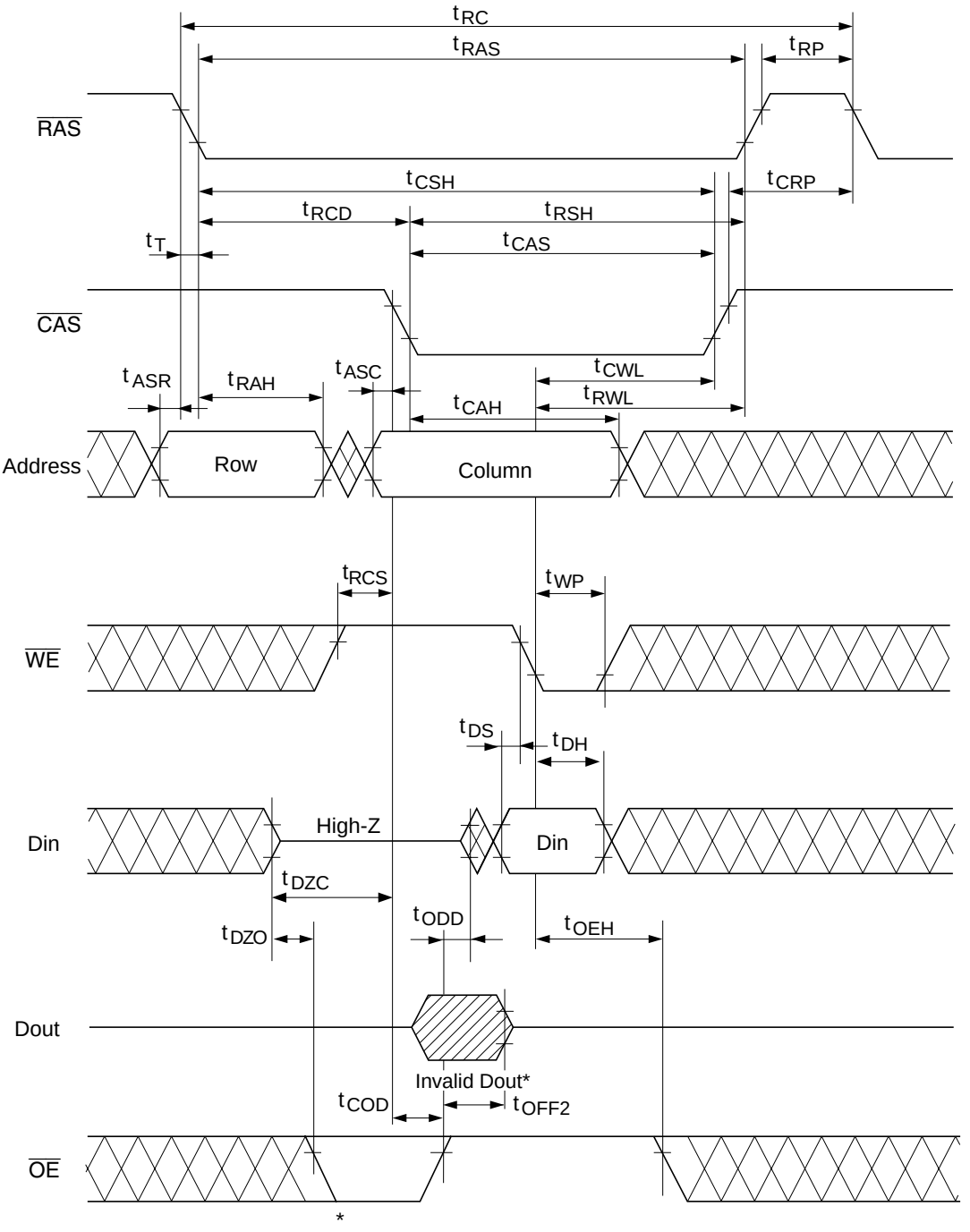
Read Cycle



Early Write Cycle

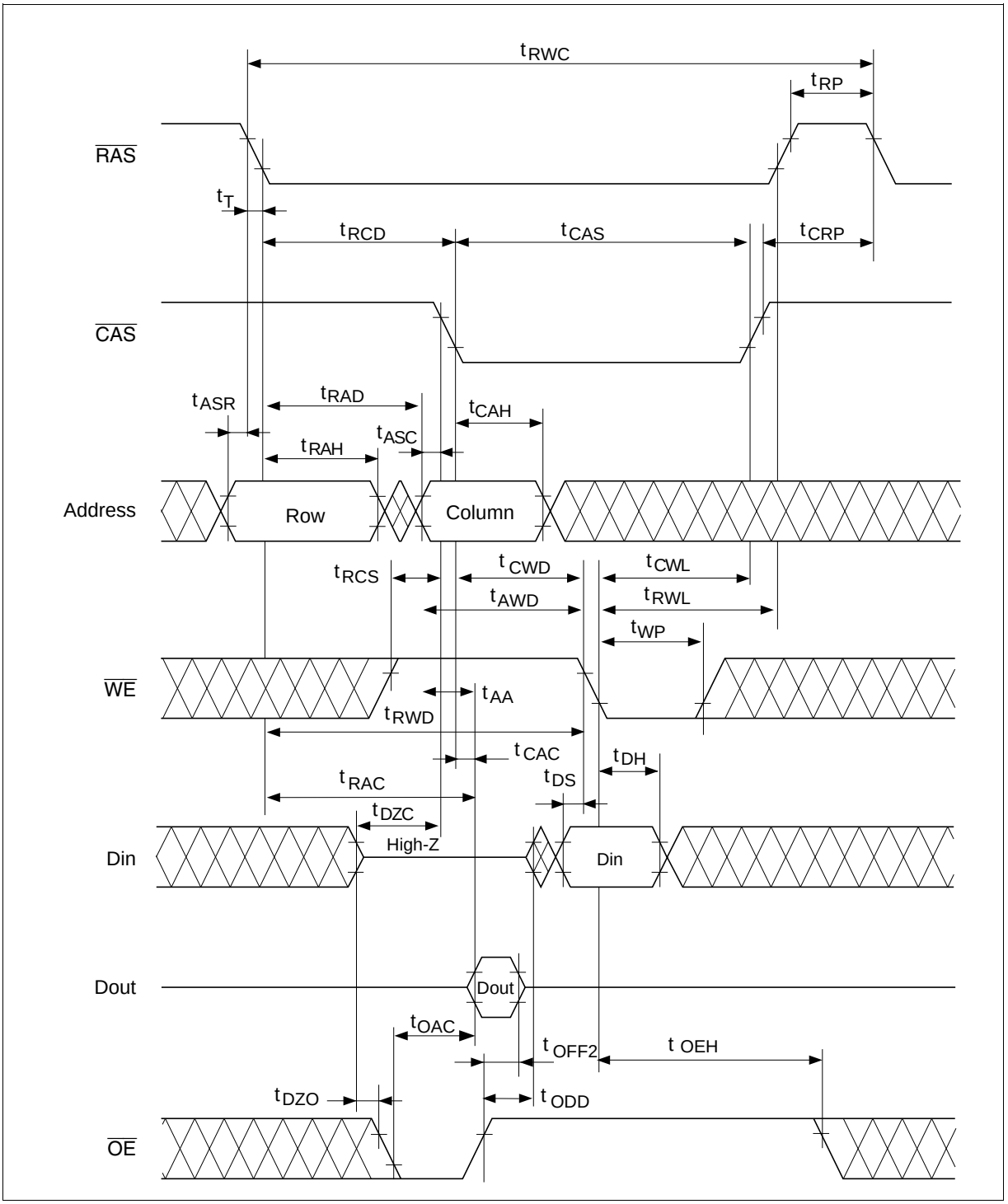


Delayed Write Cycle*[15]

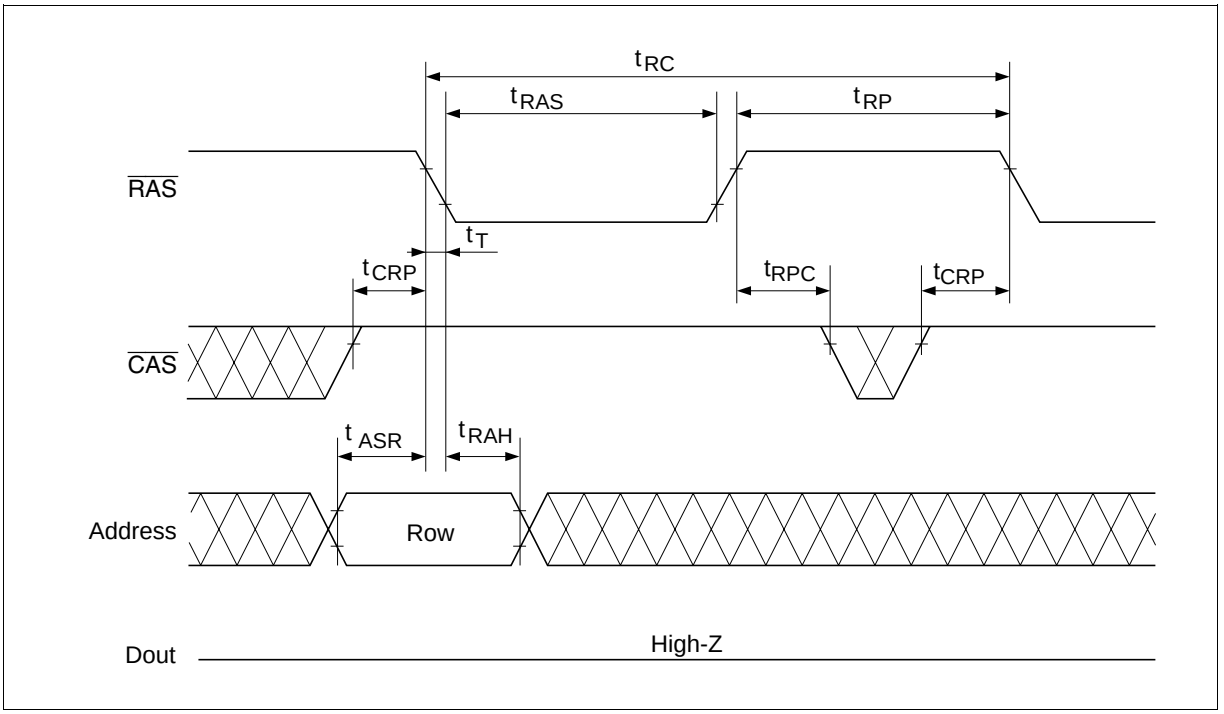


* Do not enable Dout during delayed write cycle.

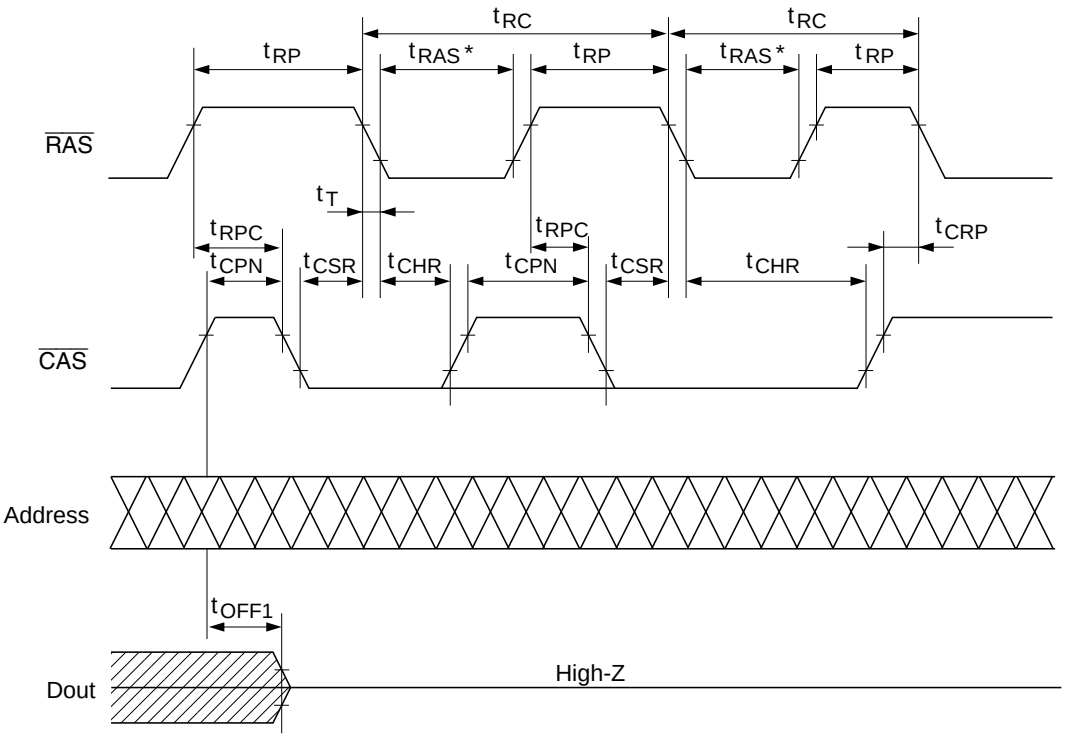
Read-Modify-Write Cycle*[15]



$\overline{\text{RAS}}$-Only Refresh Cycle

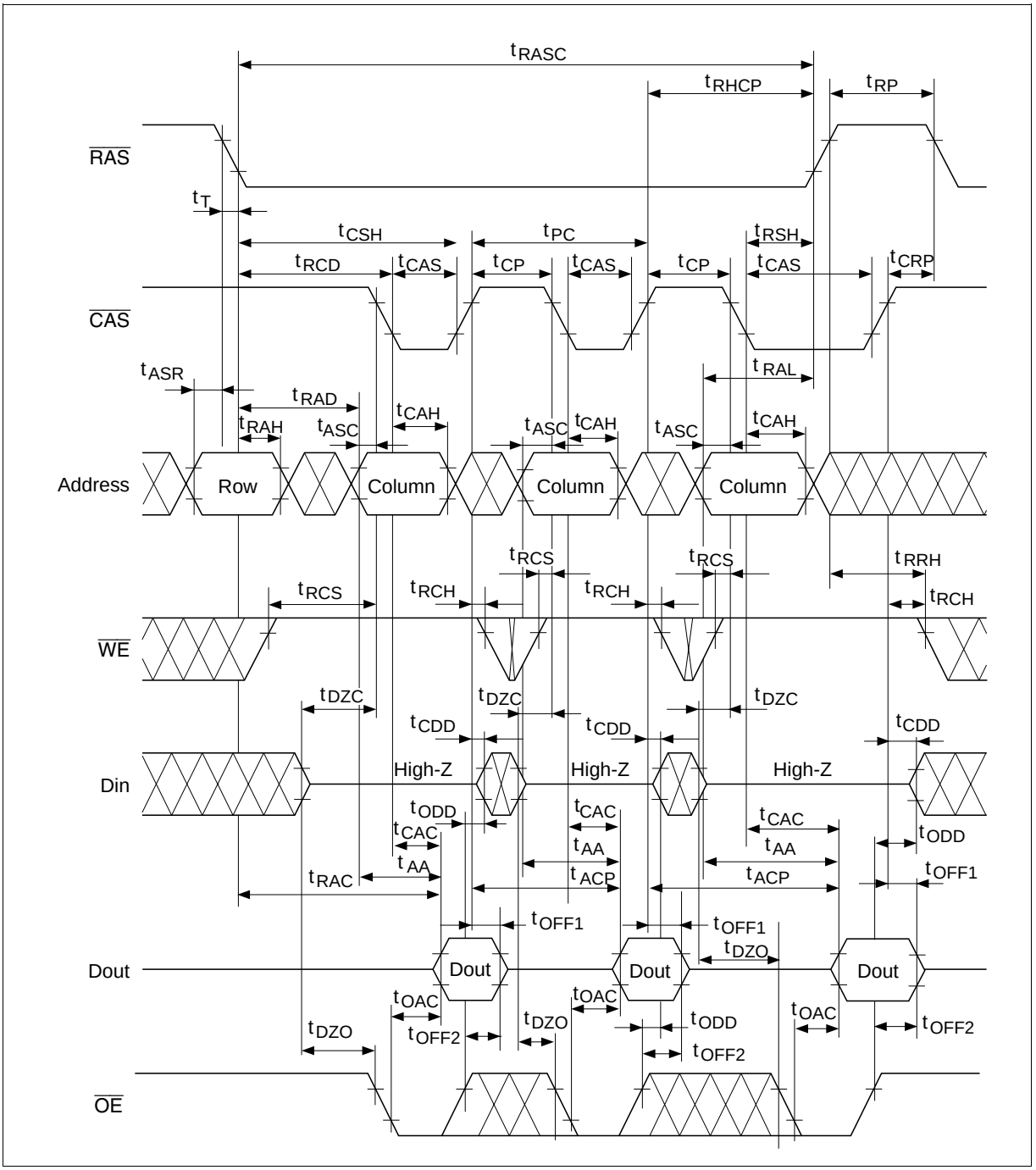


$\overline{\text{CAS}}$-Before-$\overline{\text{RAS}}$ Refresh Cycle

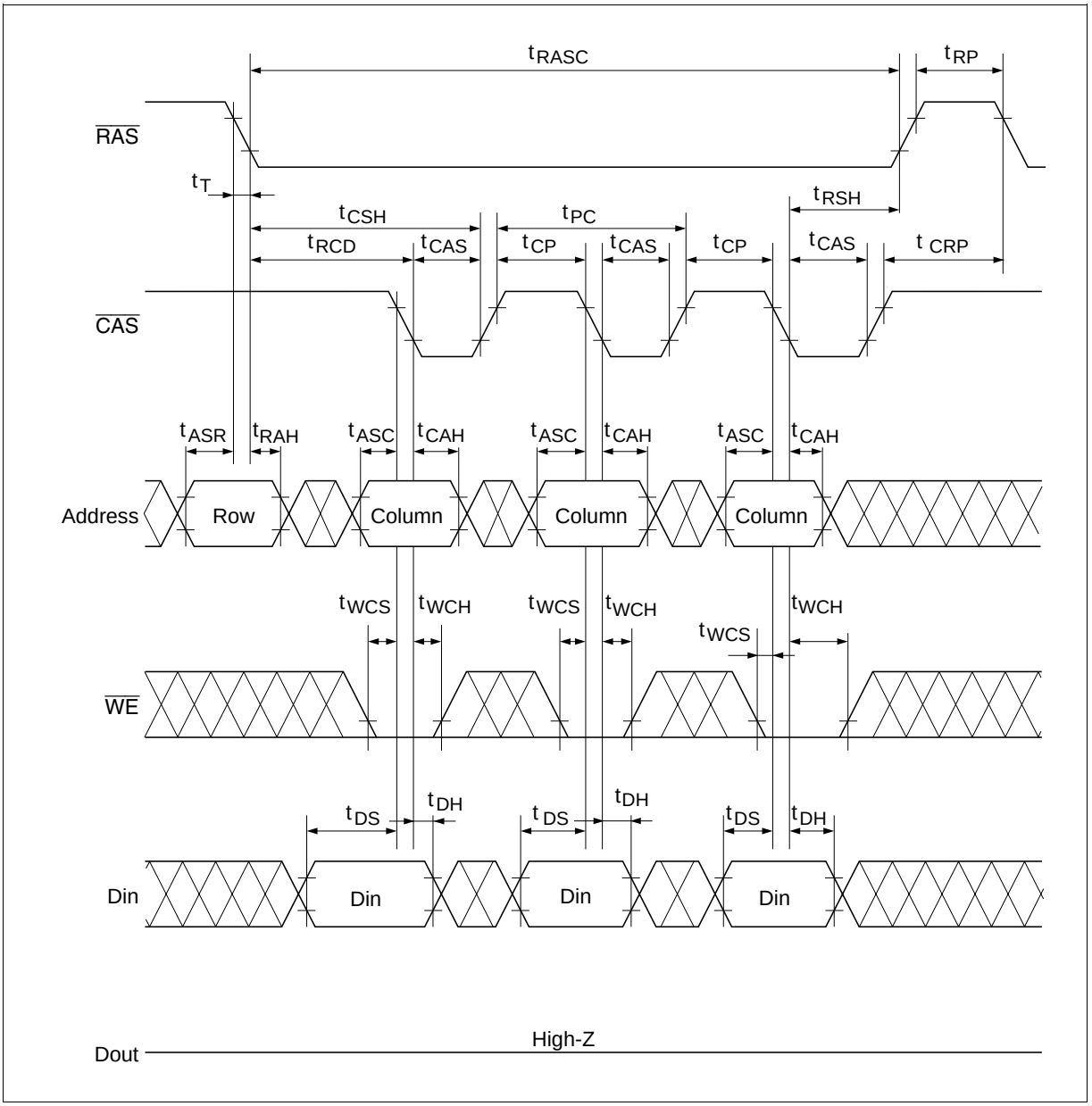


* Do not extend $t_{RAS} \geq t_{RAS}$ (max). Untested self refresh mode may be activated and loss of data may be resulted (HM514800D).

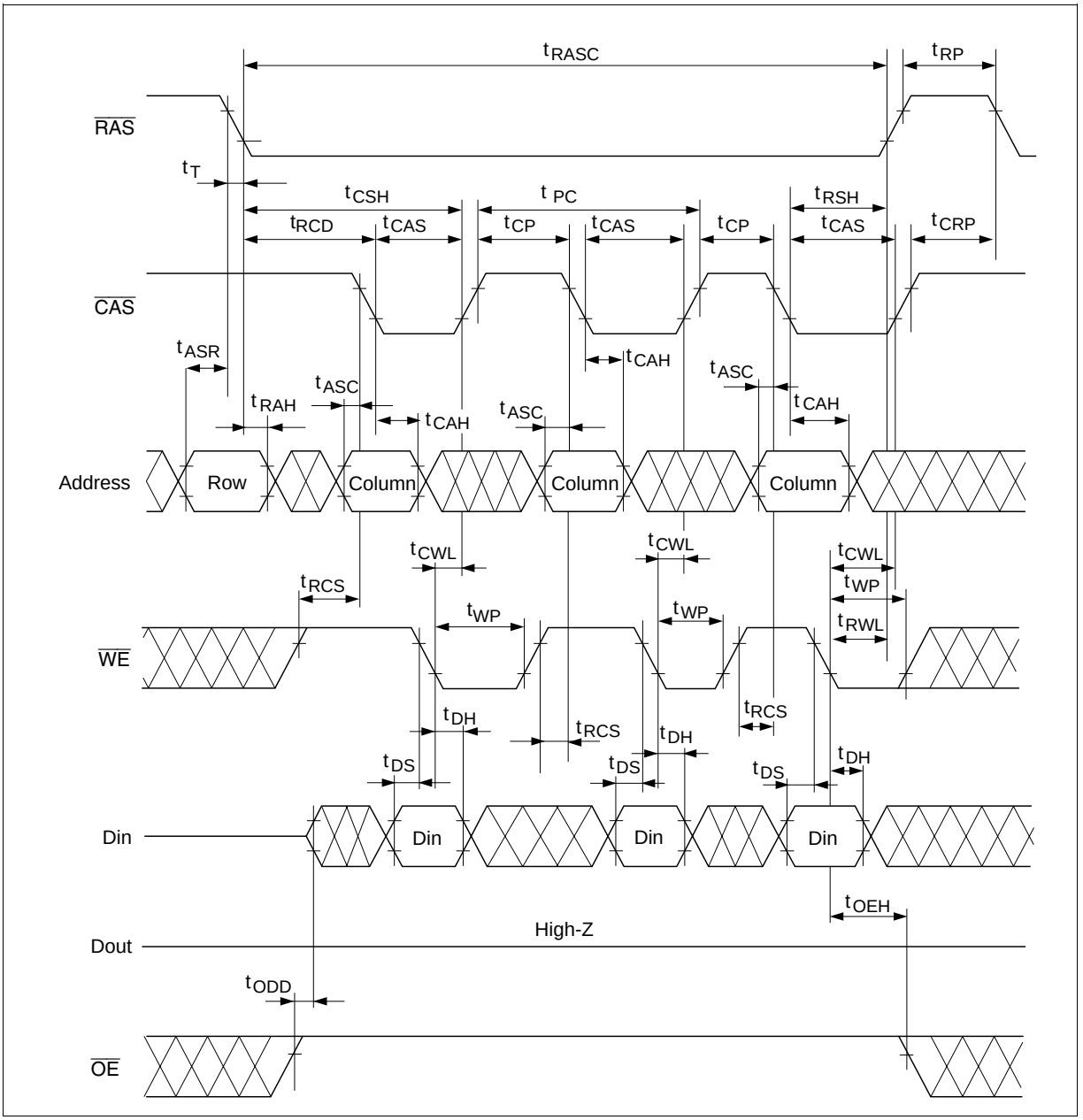
Fast Page Mode Read Cycle



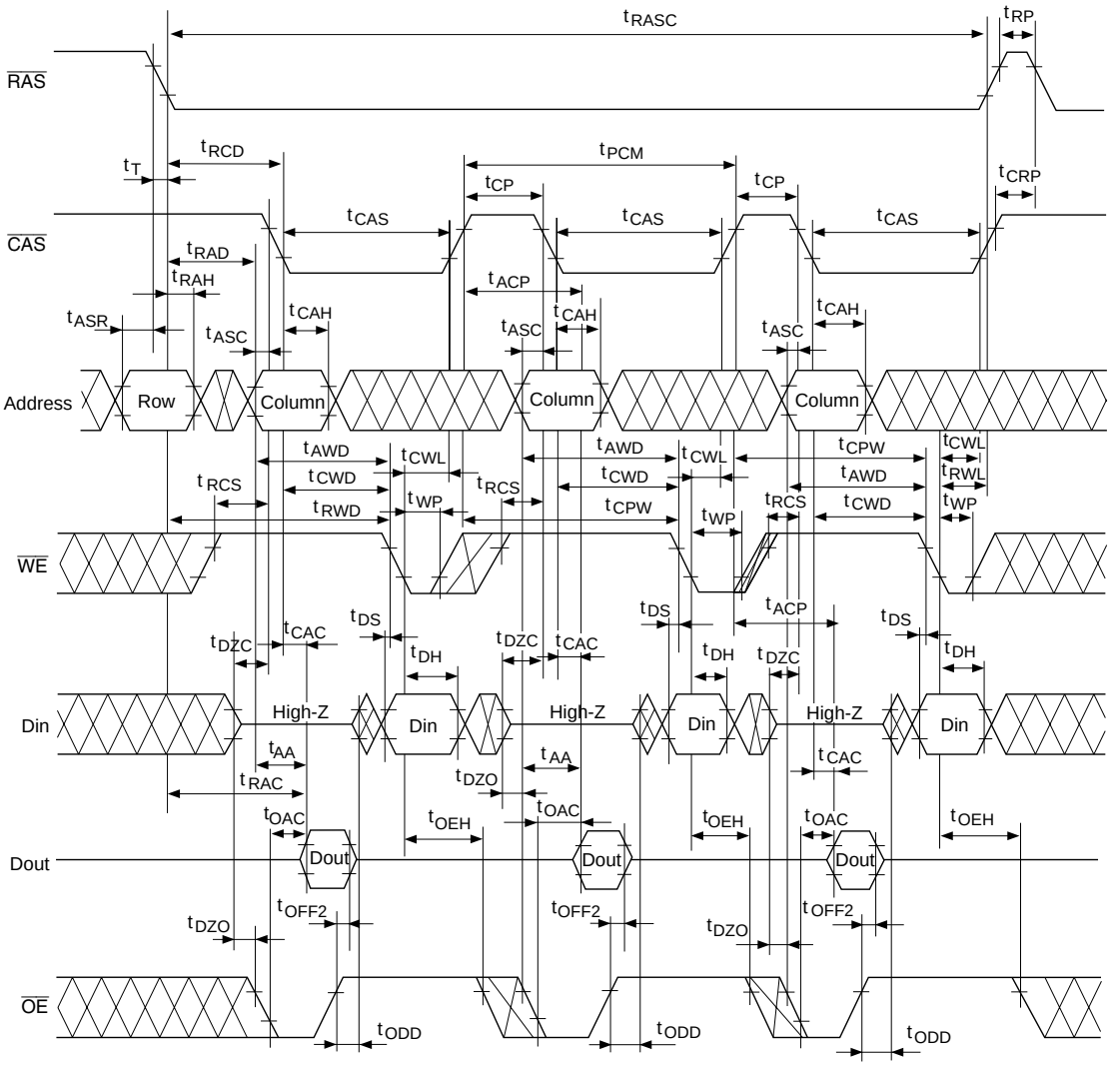
Fast Page Mode Early Write Cycle



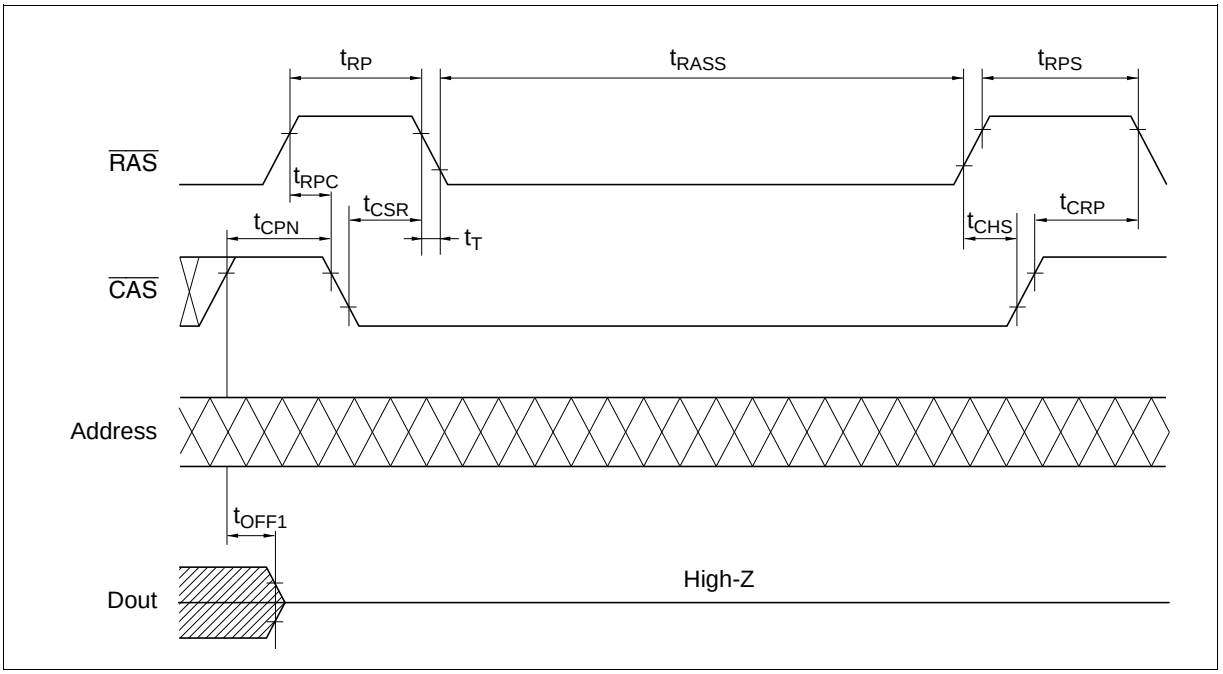
Fast Page Mode Delayed Write Cycle*[15]



Fast Page Mode Read-Modify-Write Cycle*[15]

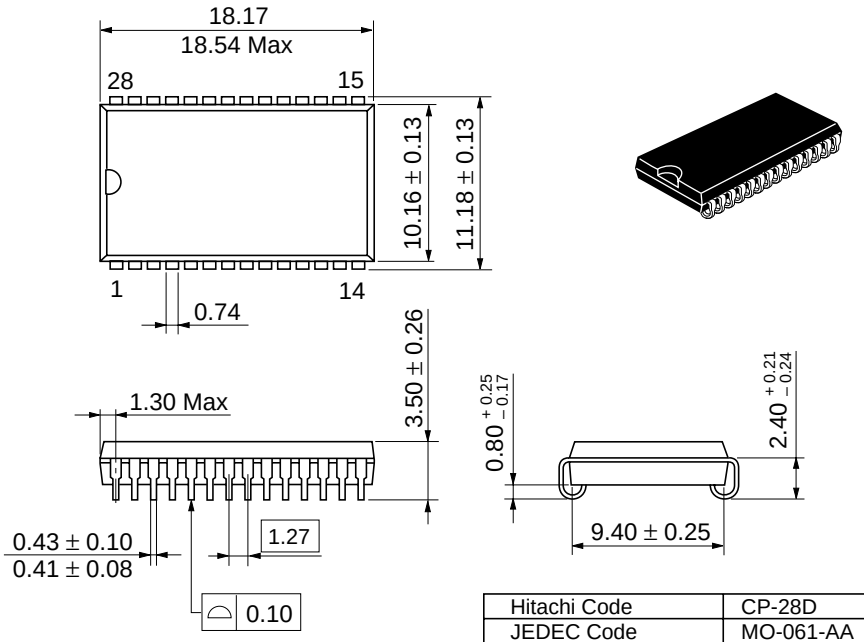


Self Refresh Cycle*[19, 20, 21, 22]



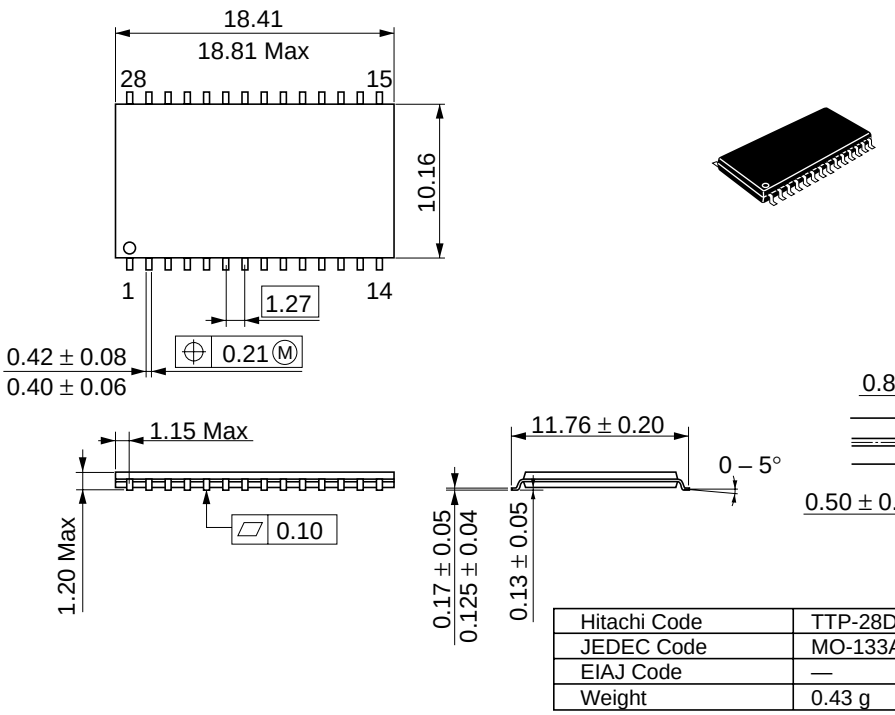
Package Dimensions

HM51(S)4800DJ/DLJ Series (CP-28D) Unit: mm



Hitachi Code	CP-28D
JEDEC Code	MO-061-AA
EIAJ Code	SC-637-B
Weight	1.16 g

HM51(S)4800DTT/DLTT Series (TTP-28D) Unit: mm



Hitachi Code	TTP-28D
JEDEC Code	MO-133AA
EIAJ Code	—
Weight	0.43 g

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Revision Record

Rev.	Date	Contents of Modification	Drawn by	Approved by
0.0	Dec. 3, 1996	Initial issue		